EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	jp-2002158191-$.did.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/15 06:46
L2	149	suemasu.in. and fujikura	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:46
L3	721917	"3" and metal	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:47
L4	52	2 and metal	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:47
L5	6933	metal with (fill or filled or filling) with (hole)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:49
L6	188	5 and (vacuum or decompression)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:49
L7	44	6 and (chamber or tank)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:49
L8	0	jp-61-144097-$.did.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/15 06:53
L9	1	jp-61144097-$.did.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/15 06:53
L10	1652	solder with (fill or filled or filling) with (hole)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:54
L11	5	10 and ((vacuum or decompression or pressurized) near5 (chamber or tank))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 06:54

L12	263	solder with (hole) with (dip or dipped or dipping or immerse or immersion or immersing)	USPAT	OR	ON	2010/01/15 06:56
L13	12	12 same (vacuum or decompression or pressure or pressurized or pressurizing)	USPAT	OR	ON	2010/01/15 06:56
L14	91	solder with (hole) with (dip or dipped or dipping or immerse or immersion or immersing)	US-PGPUB	OR	ON	2010/01/15 06:58
L15	7	14 same (vacuum or decompression or pressure or pressurized or pressurizing)	US-PGPUB	OR	ON	2010/01/15 06:58
L16	12735	solder same (vacuum or decompression or pressure or pressurized or pressurizing)	USPAT	OR	ON	2010/01/15 06:58
L17	1009	solder same ((vacuum or decompression or pressure or pressurized or pressurizing) near5 (vessel or tank or chamber))	USPAT	OR	ON	2010/01/15 06:58
L18	379	17 and ((circuit or wiring) near5 (board))	USPAT	OR	ON	2010/01/15 06:59
L19	93	(solder near5 (molten)) same ((vacuum or decompression or pressure or pressurizing) near5 (vessel or tank or chamber))	USPAT	OR	ON	2010/01/15 07:00
L20	49	19 and ((circuit or wiring) near5 (board))	USPAT	OR	ON	2010/01/15 07:00
L21	8	(solder near5 (molten)) near20 ((vacuum or decompression or pressure or pressurized or pressurizing) near5 (vessel or tank or chamber))	USOCR	OR	ON	2010/01/15 07:06
L22	91	(solder) near20 ((vacuum or decompression or pressure or pressurized or pressurizing) near5 (vessel or tank or chamber))	USOCR	OR	ON	2010/01/15 07:07
L23	0	22 and ((circuit or wiring) near5 (board))	US-PGPUB	OR	ON	2010/01/15 07:07

L24	10	22 and ((circuit or wiring) near5 (board))	USOCR	OR	ON	2010/01/15 07:08
L25	25	((solder) near5 (dipped or diped or dippng or immerse or immersed or immering)) and ((vacuum or decompression or pressure or pressurized or pressurizing) near5 (vessel or tank or chamber))	USOCR	OR	ON	2010/01/15 07:08
L26	133	((solder) near5 (dipped or diped or dippng or immerse or immersed or immering)) and ((vacuum or decompression or pressure or pressurized or pressurizing) near5 (vessel or tank or chamber))	USPAT	OR	ON	2010/01/15 07:10
L27	81	26 and ((circuit or wiring) near5 (board))	USPAT	OR	ON	2010/01/15 07:10
L28	87696	(molten near2 (solder or metal))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 07:15
L29	5306	28 near10 (hole)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 07:15
L30	496	29 and (dipped or dipping or dipped or immerse or immersing or immersion or immersed)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 07:16
L31	100	30 and (pressure or pressurized or pressurizing or vacuum or decompress or decompressed or decompression or suction)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 07:16
L32	1967	(molten near2 (solder or metal)) near10 hole	USPAT	OR	ON	2010/01/15 07:23
L33	149	32 same (dipped or dipping or dipped or immerse or immersing or immersed)	USPAT	OR	ON	2010/01/15 07:24
L34	25	33 same (pressure or pressurized or pressurizing or vacuum or decompress or decompressed or decompression or suction)	USPAT	OR	ON	2010/01/15 07:24
L35	464	(liquid near2 (solder or metal)) near10 hole	USPAT	OR	ON	2010/01/15 07:27

L36	31	35 same (dipped or dipping or dipped or immerse or immersing or immersion or immersed)	USPAT	OR	ON	2010/01/15 07:27
L37	8922	(solder) near10 hole	USPAT	OR	ON	2010/01/15 07:28
L38	385	37 same (dipped or dipping or dipped or immerse or immersing or immersion or immersed)	USPAT	OR	ON	2010/01/15 07:28
L39	45	38 same (pressure or pressurized or pressurizing or vacuum or decompress or decompressed or decompression or suction)	USPAT	OR	ON	2010/01/15 07:28
L40	2	jp-08238565-$.did.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/15 07:31
L41	1932	((427/97.2) or (427/97.3) or (427/97.7) or (427/431)).CCLS.	US-PGPUB; USPAT	OR	OFF	2010/01/15 07:48
L42	28	41 and @pd>"20090819"	US-PGPUB; USPAT	OR	ON	2010/01/15 07:48

EAST Search History (Interference)

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1/15/10 7:49:27 AM
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